

TITLE OF INVENTION:	Perforated Plate for Wafer Chuck
APPLICANT: ADDRESS:	✓ Systems on Silicon Manufacturing Co. Pte. Ltd. 70, Pasir Ris Industrial Drive 1 Singapore 519527 Singapore
INVENTOR 1: ADDRESS:	✓ M <u>ENG FEI KOH</u> Blk 3, Dover Road #07-354 Singapore 130003 Singapore
COUNTRY OF PERMANENT RESIDENCY: NATIONALITY:	SINGAPORE MALAYSIAN (SINGAPORE PERMANENT RESIDENCE)
INVENTOR 2: ADDRESS:	✓ C <u>HOON SIONG POH</u> Blk 360C, Admiralty Road #12-36 Singapore 753360 Singapore
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INVENTOR 5:
ADDRESS:

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COUNTRY OF PERMANENT
RESIDENCY:
NATIONALITY:

SINGAPORE
CHINESE (SINGAPORE PERMANENT
RESIDENCE)

PRIORITY TO BE CLAIMED:-

None

INTERNATIONAL APPLICATION NO.

PCT/SG03/00170

INTERNATIONAL FILING DATE:

14 JULY 2003